

# Przemyslaw Gromala

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/3740692/publications.pdf>

Version: 2024-02-01

12  
papers

49  
citations

2258059

3  
h-index

2550090

3  
g-index

12  
all docs

12  
docs citations

12  
times ranked

32  
citing authors

#	ARTICLE	IF	CITATIONS
1	Accuracy of CMOS-Based Piezoresistive Stress Sensor for Engineering Applications of Thermal Loading Condition: Theoretical Review and Experimental Validation. IEEE Sensors Journal, 2019, 19, 9139-9148.	4.7	12
2	Prognostic approaches for the wirebond failure prediction in power semiconductors: A case study using DPAK package. , 2015, , .		10
3	&lt;inline-formula&gt; &lt;tex-math notation="LaTeX"&gt;\$In Situ\$ &lt;/tex-math&gt; &lt;/inline-formula&gt; Failure Detection of Electronic Control Units Using Piezoresistive Stress Sensor. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 750-763.	2.5	10
4	Study of Thermal Aging Behavior of Epoxy Molding Compound for Applications in Harsh Environments. , 2019, , .		8
5	Concept of the 3<sup>rd</sup> Generation of Reliability for Electronic Smart Systems. , 2019, , .		4
6	In-situ service load monitoring of automotive electronic systems using silicon-based piezoresistive stress sensor. Microelectronics Reliability, 2020, 110, 113650.	1.7	3
7	Simulation Driven Design of Novel Integrated Circuits - Part 4: Method of Validation of Coupled Thermal and Thermo-mechanical Simulation. , 2018, , .		1
8	Characterization of toughness of epoxy based molding compound and its implementation in FEM code. , 2020, , .		1
9	Simulation Driven Design of Novel Integrated Circuits -- Physics of Failure Simulation of the Electronic Control Modules for Harsh Environment Application. , 2016, , .		0
10	Effect of Time-Dependent Bulk Modulus on Reliability Assessment of Automotive Electronic Control Unit. , 2019, , .		0
11	Evaluation of Chip-Package Interaction by Means of Stress Sensors. IEEE Sensors Journal, 2022, 22, 12959-12966.	4.7	0
12	In-situ monitoring of thermo-mechanical induced stresses in electronic control unit " from the assembly to use in the field. , 2022, , .		0